

# QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

SCES131H – MARCH 1998 – REVISED APRIL 2005

- 2-V to 5.5-V  $V_{CC}$  Operation
- Max  $t_{pd}$  of 6.5 ns at 5 V
- Typical  $V_{OLP}$  (Output Ground Bounce)  $<0.8$  V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Typical  $V_{OHV}$  (Output  $V_{OH}$  Undershoot)  $>2.3$  V at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- Support Mixed-Mode Voltage Operation on All Ports
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

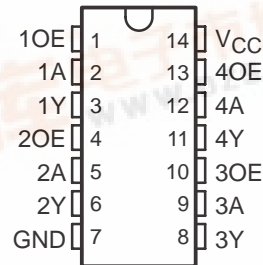
## description/ordering information

These quadruple bus buffer gates are designed for 2-V to 5.5-V  $V_{CC}$  operation.

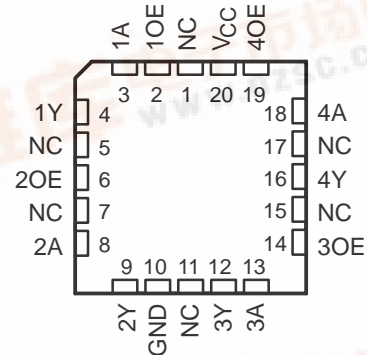
The 'LV126A devices feature independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable (OE) input is low.

To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

SN54LV126A ... J OR W PACKAGE  
SN74LV126A ... D, DB, DGV, NS, OR PW PACKAGE  
(TOP VIEW)



SN54LV126A ... FK PACKAGE  
(TOP VIEW)



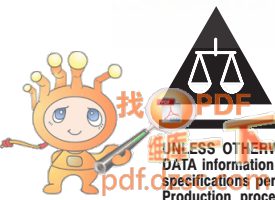
NC – No internal connection

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
–40°C to 85°C	SOIC – D	Tube of 50	SN74LV126AD	LV126A	
		Reel of 2500	SN74LV126ADR		
	SOP – NS	Reel of 2000	SN74LV126ANSR	74LV126A	
	SSOP – DB	Reel of 2000	SN74LV126ADBR	LV126A	
			Tube of 90	SN74LV126APW	LV126A
			Reel of 2000	SN74LV126APWR	
Reel of 250	SN74LV126APWT				
–55°C to 125°C	TVSOP – DGV	Reel of 2000	SN74LV126ADGVR	LV126A	
	CDIP – J	Tube of 25	SNJ54LV126AJ	SNJ54LV126AJ	
	CFP – W	Tube of 150	SNJ54LV126AW	SNJ54LV126AW	
	LCCC – FK	Tube of 55	SNJ54LV126AFK	SNJ54LV126AFK	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



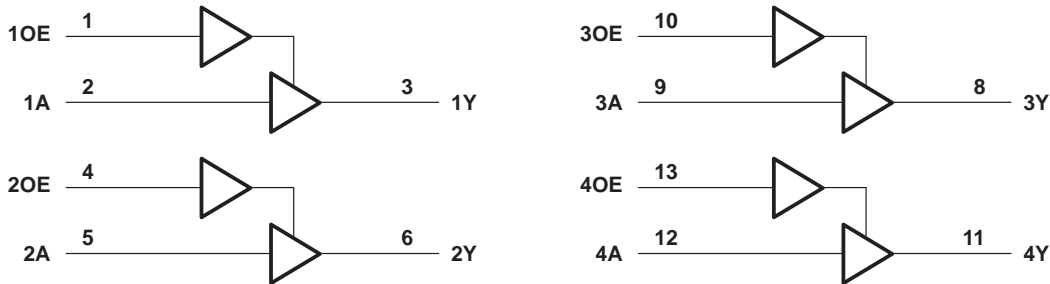
# SN54LV126A, SN74LV126A QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

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FUNCTION TABLE  
(each buffer)

INPUTS		OUTPUT
OE	A	Y
H	H	H
H	L	L
L	X	Z

## logic diagram (positive logic)



Pin numbers shown are for the D, DB, DGV, J, NS, PW, and W packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, $V_O$ (see Note 1)	-0.5 V to 7 V
Output voltage range, $V_O$ (see Notes 1 and 2)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	-20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	-50 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	$\pm 35$ mA
Continuous current through $V_{CC}$ or GND	$\pm 70$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 3):	
D package	86°C/W
DB package	96°C/W
DGV package	127°C/W
NS package	76°C/W
PW package	113°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
  2. This value is limited to 5.5 V maximum.
  3. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN54LV126A, SN74LV126A QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

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## recommended operating conditions (see Note 4)

		SN54LV126A		SN74LV126A		UNIT	
		MIN	MAX	MIN	MAX		
V <sub>CC</sub>	Supply voltage	2	5.5	2	5.5	V	
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5		1.5	V	
		V <sub>CC</sub> = 2.3 V to 2.7 V	V <sub>CC</sub> × 0.7		V <sub>CC</sub> × 0.7		
		V <sub>CC</sub> = 3 V to 3.6 V	V <sub>CC</sub> × 0.7		V <sub>CC</sub> × 0.7		
		V <sub>CC</sub> = 4.5 V to 5.5 V	V <sub>CC</sub> × 0.7		V <sub>CC</sub> × 0.7		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V		0.5	0.5	V	
		V <sub>CC</sub> = 2.3 V to 2.7 V		V <sub>CC</sub> × 0.3	V <sub>CC</sub> × 0.3		
		V <sub>CC</sub> = 3 V to 3.6 V		V <sub>CC</sub> × 0.3	V <sub>CC</sub> × 0.3		
		V <sub>CC</sub> = 4.5 V to 5.5 V		V <sub>CC</sub> × 0.3	V <sub>CC</sub> × 0.3		
V <sub>I</sub>	Input voltage	0	5.5	0	5.5	V	
V <sub>O</sub>	Output voltage	High or low state	0	V <sub>CC</sub>	0	V <sub>CC</sub>	V
		3-state	0	5.5	0	5.5	
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2 V		-50	-50	μA	
		V <sub>CC</sub> = 2.3 V to 2.7 V		-2	-2	mA	
		V <sub>CC</sub> = 3 V to 3.6 V		-8	-8		
		V <sub>CC</sub> = 4.5 V to 5.5 V		-16	-16		
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2 V		50	50	μA	
		V <sub>CC</sub> = 2.3 V to 2.7 V		2	2	mA	
		V <sub>CC</sub> = 3 V to 3.6 V		8	8		
		V <sub>CC</sub> = 4.5 V to 5.5 V		16	16		
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 2.3 V to 2.7 V		200	200	ns/V	
		V <sub>CC</sub> = 3 V to 3.6 V		100	100		
		V <sub>CC</sub> = 4.5 V to 5.5 V		20	20		
T <sub>A</sub>	Operating free-air temperature	-55	125	-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	SN54LV126A			SN74LV126A			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	2 V to 5.5 V	V <sub>CC</sub> -0.1			V <sub>CC</sub> -0.1		V	
	I <sub>OH</sub> = -2 mA	2.3 V	2			2			
	I <sub>OH</sub> = -8 mA	3 V	2.48			2.48			
	I <sub>OH</sub> = -16 mA	4.5 V	3.8			3.8			
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	2 V to 5.5 V			0.1			V	
	I <sub>OL</sub> = 2 mA	2.3 V			0.4		0.4		
	I <sub>OL</sub> = 8 mA	3 V			0.44		0.44		
	I <sub>OL</sub> = 16 mA	4.5 V			0.55		0.55		
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V			±1		±1	μA	
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or GND	5.5 V			±5		±5	μA	
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V			20		20	μA	
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 0 to 5.5 V	0			5		5	μA	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		1.6		1.6		pF	

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.

# SN54LV126A, SN74LV126A QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LV126A		SN74LV126A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	Y	$C_L = 15\text{ pF}$	7.1*	13*	1*	15.5*	1	15.5	ns	
$t_{en}$	OE	Y		7.4*	13*	1*	15.5*	1	15.5		
$t_{dis}$	OE	Y		5.7*	14.7*	1*	17*	1	17		
$t_{pd}$	A	Y	$C_L = 50\text{ pF}$	9.2	16.5	1	18.5	1	18.5	ns	
$t_{en}$	OE	Y		9.5	16.5	1	18.5	1	18.5		
$t_{dis}$	OE	Y		8.1	18.2	15	20.5	1	20.5		
$t_{sk(o)}$						2			2		

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LV126A		SN74LV126A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	Y	$C_L = 15\text{ pF}$	5*	8*	1*	9.5*	1	9.5	ns	
$t_{en}$	OE	Y		5.1*	8*	1*	9.5*	1	9.5		
$t_{dis}$	OE	Y		4.4*	9.7*	1*	11.5*	1	11.5		
$t_{pd}$	A	Y	$C_L = 50\text{ pF}$	6.4	11.5	1	13	1	13	ns	
$t_{en}$	OE	Y		6.6	11.5	1	13	1	13		
$t_{dis}$	OE	Y		6.1	13.2	1	15	1	15		
$t_{sk(o)}$						1.5			1.5		

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LV126A		SN74LV126A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	Y	$C_L = 15\text{ pF}$	3.5*	5.5*	1*	6.5*	1	6.5	ns	
$t_{en}$	OE	Y		3.6*	5.1*	1*	6*	1	6		
$t_{dis}$	OE	Y		3.3*	6.8*	1*	8*	1	8		
$t_{pd}$	A	Y	$C_L = 50\text{ pF}$	4.6	7.5	1	8.5	1	8.5	ns	
$t_{en}$	OE	Y		4.6	7.1	1	8	1	8		
$t_{dis}$	OE	Y		4.3	8.8	1	10	1	10		
$t_{sk(o)}$						1			1		

\* On products compliant to MIL-PRF-38535, this parameter is not production tested.

**SN54LV126A, SN74LV126A**  
**QUADRUPLE BUS BUFFER GATES**  
**WITH 3-STATE OUTPUTS**

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**noise characteristics,  $V_{CC} = 3.3\text{ V}$ ,  $C_L = 50\text{ pF}$ ,  $T_A = 25^\circ\text{C}$  (see Note 5)**

PARAMETER		SN74LV126A			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic $V_{OL}$		0.3	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic $V_{OL}$		-0.2	-0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic $V_{OH}$		3.1		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.97	V

NOTE 5: Characteristics are for surface-mount packages only.

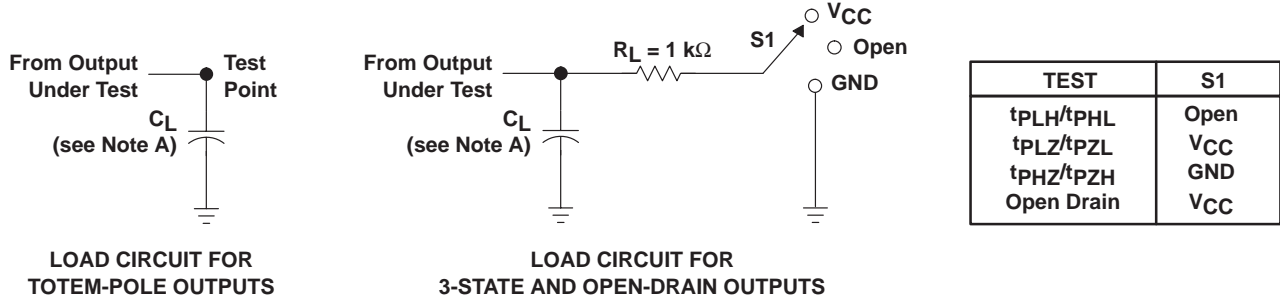
**operating characteristics,  $T_A = 25^\circ\text{C}$**

PARAMETER		TEST CONDITIONS	$V_{CC}$	TYP	UNIT
$C_{pd}$	Power dissipation capacitance		Outputs enabled $C_L = 50\text{ pF}$ , $f = 10\text{ MHz}$	3.3 V	
		5 V		15.9	

# SN54LV126A, SN74LV126A QUADRUPLE BUS BUFFER GATES WITH 3-STATE OUTPUTS

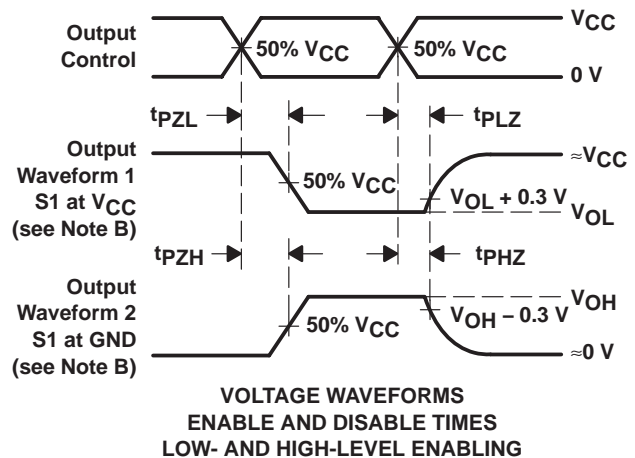
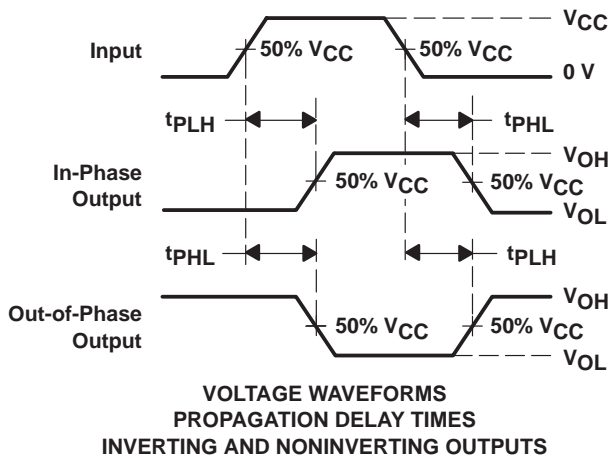
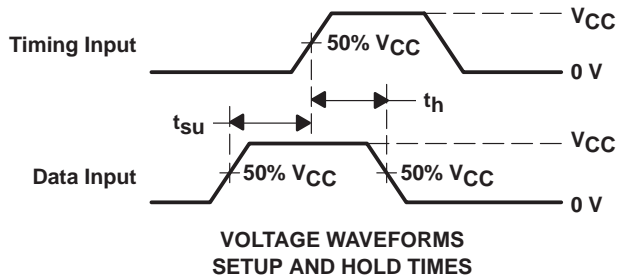
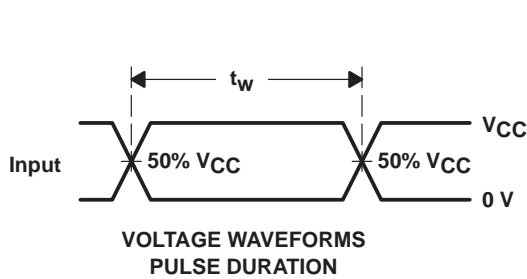
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## PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT FOR  
TOTEM-POLE OUTPUTS

LOAD CIRCUIT FOR  
3-STATE AND OPEN-DRAIN OUTPUTS



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 3$  ns,  $t_f \leq 3$  ns.
  - D. The outputs are measured one at a time, with one input transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PHL}$  and  $t_{PLH}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LV126AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ADGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ADGVRE4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ADGVRG4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126APWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV126APWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

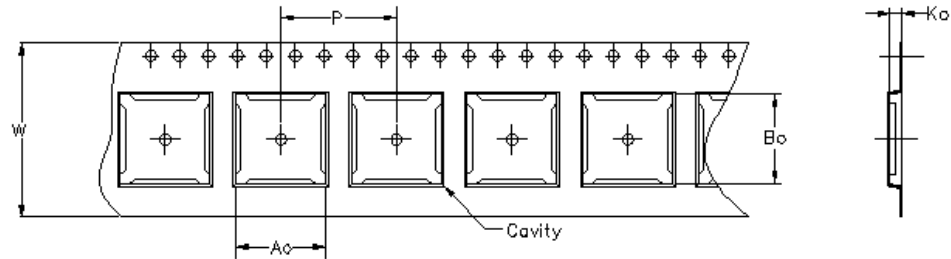
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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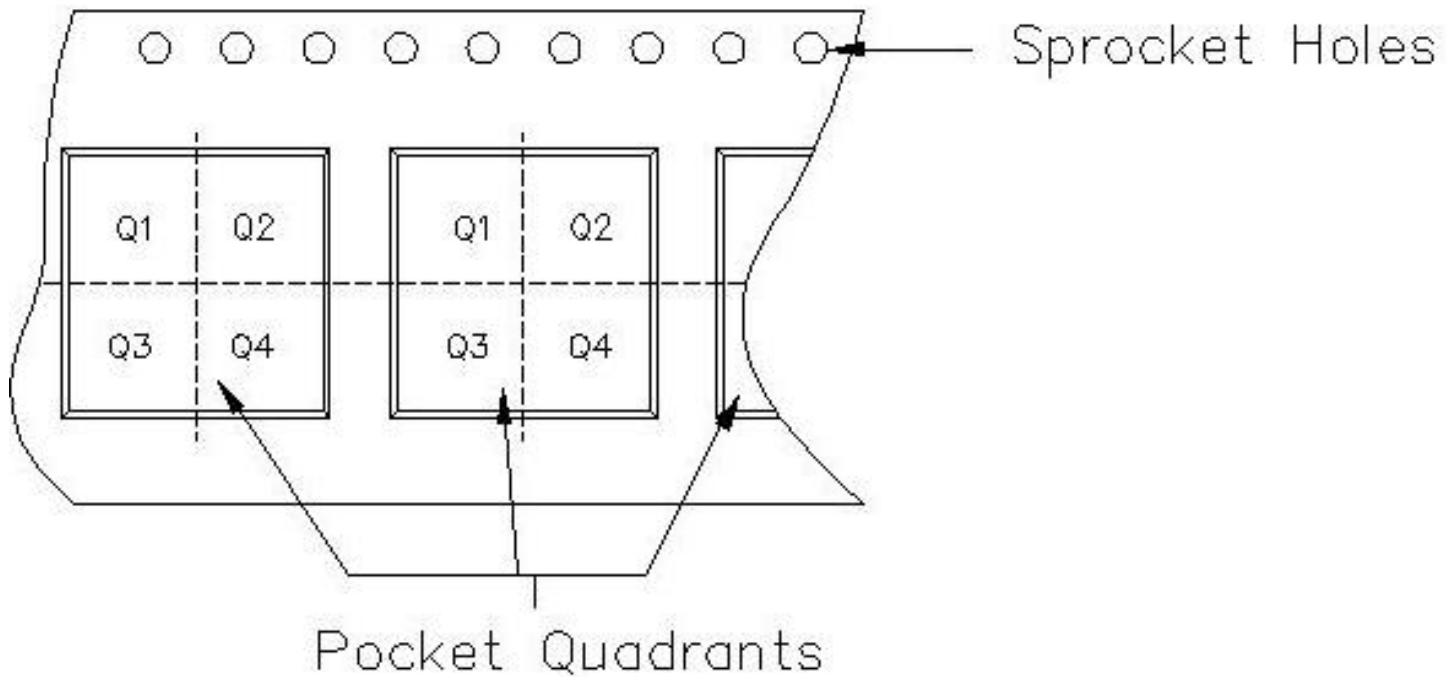
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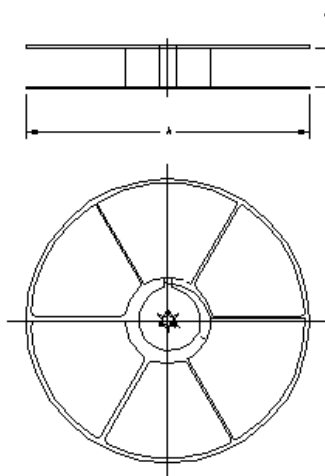
Carrier tape design is defined largely by the component length, width, and thickness.

$A_0$ = Dimension designed to accommodate the component width.
$B_0$ = Dimension designed to accommodate the component length.
$K_0$ = Dimension designed to accommodate the component thickness.
$W$ = Overall width of the carrier tape.
$P$ = Pitch between successive cavity centers.



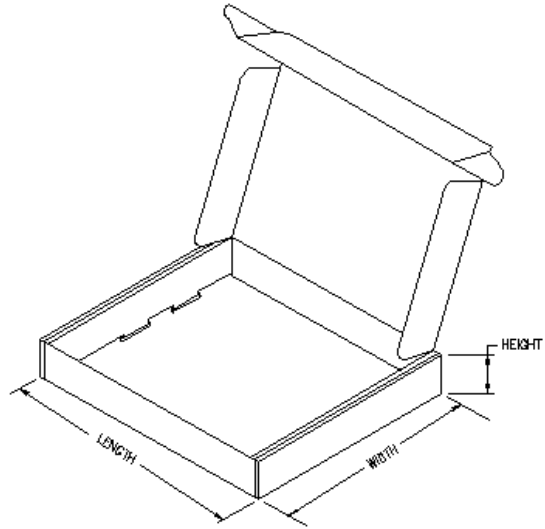
**TAPE AND REEL INFORMATION**

Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV126ADBR	DB	14	MLA	330	16	8.2	6.6	2.5	12	16	Q1
SN74LV126ADGVR	DGV	14	MLA	330	12	6.8	4.0	1.6	8	16	Q1
SN74LV126ADR	D	14	MLA	330	16	6.5	9.0	2.1	8	16	Q1
SN74LV126ANSR	NS	14	MLA	330	16	8.2	10.5	2.5	12	16	Q1
SN74LV126APWR	PW	14	MLA	330	12	7.0	5.6	1.6	8	12	Q1



**TAPE AND REEL BOX INFORMATION**

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74LV126ADBR	DB	14	MLA	342.9	336.6	28.58
SN74LV126ADGVR	DGV	14	MLA	338.1	340.5	20.64
SN74LV126ADR	D	14	MLA	342.9	336.6	28.58
SN74LV126ANSR	NS	14	MLA	342.9	336.6	28.58
SN74LV126APWR	PW	14	MLA	338.1	340.5	20.64



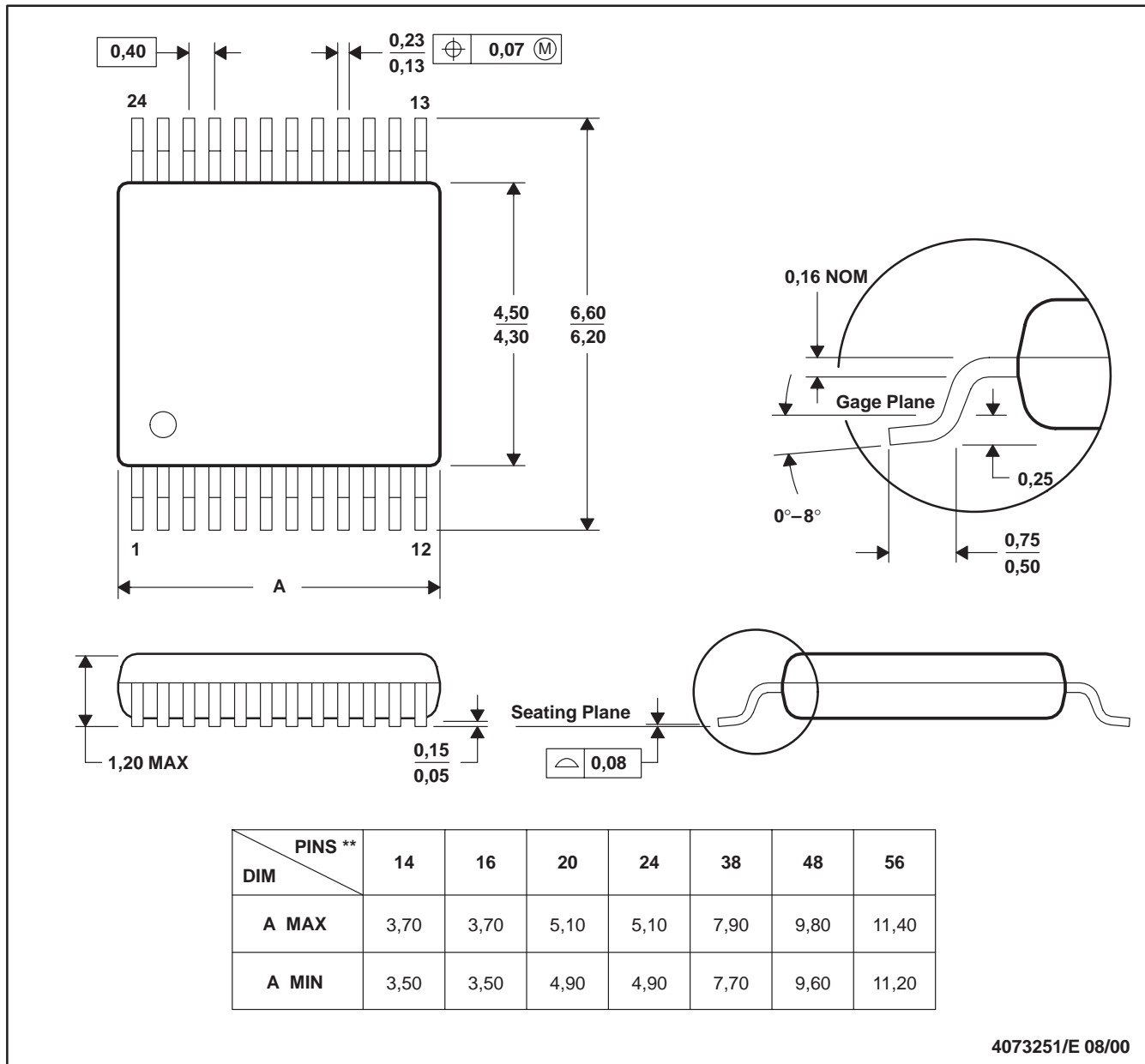
# MECHANICAL DATA

MPDS006C – FEBRUARY 1996 – REVISED AUGUST 2000

## DGV (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

24 PINS SHOWN

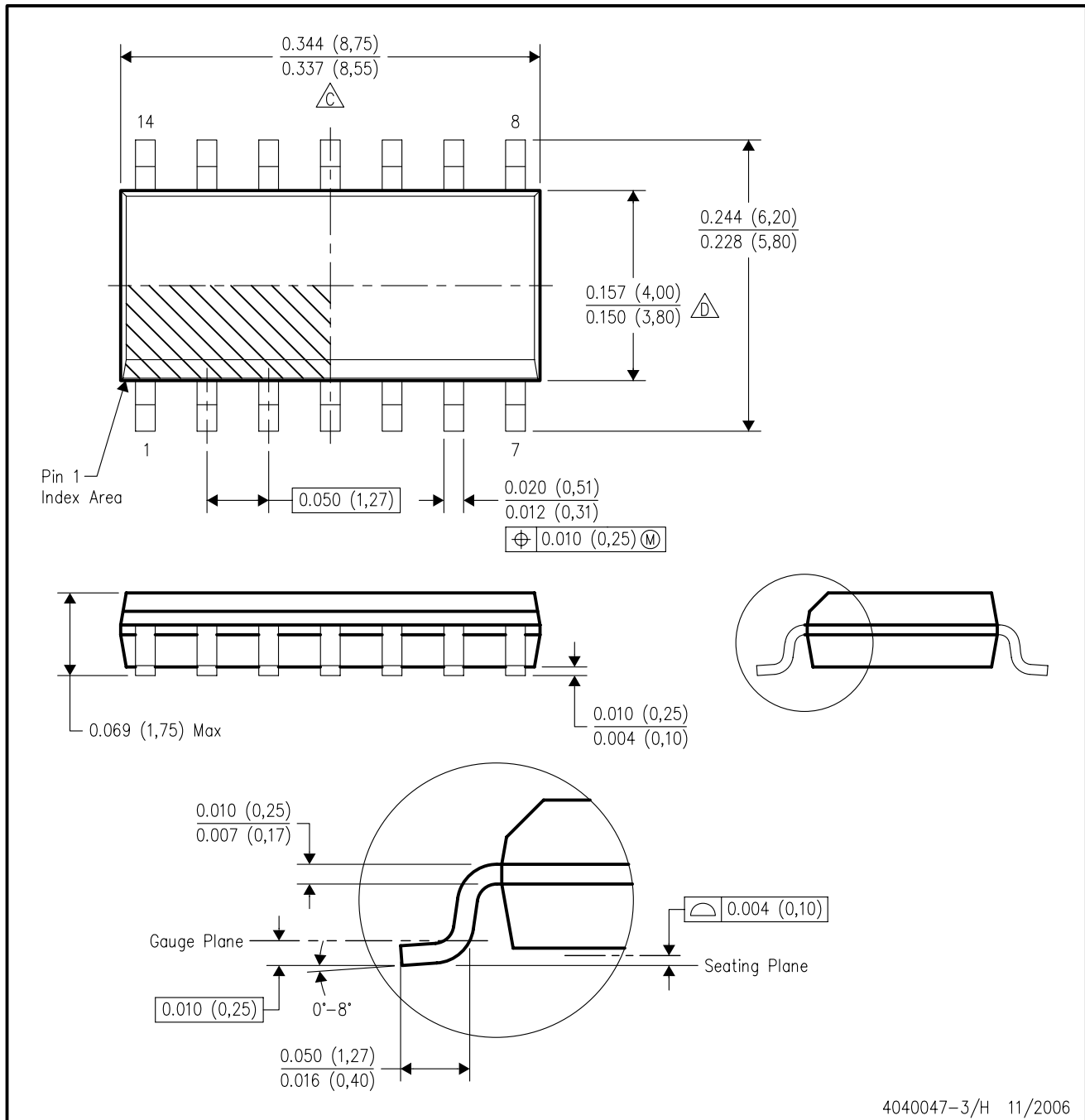


- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

# MECHANICAL DATA

## D (R-PDSO-G14)

## PLASTIC SMALL-OUTLINE PACKAGE



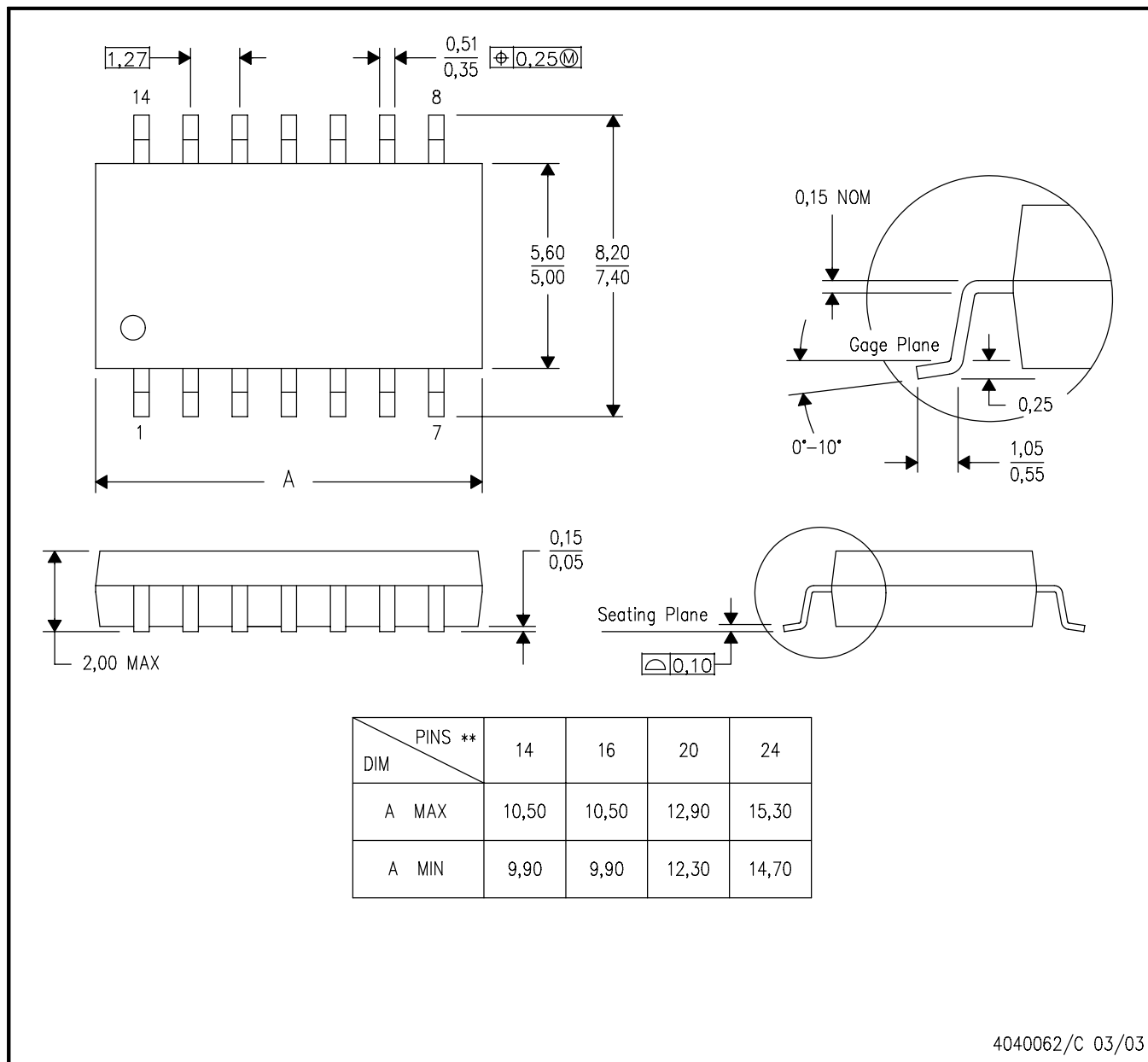
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - △ C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - △ D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AB.

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

**14-PINS SHOWN**



4040062/C 03/03

- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

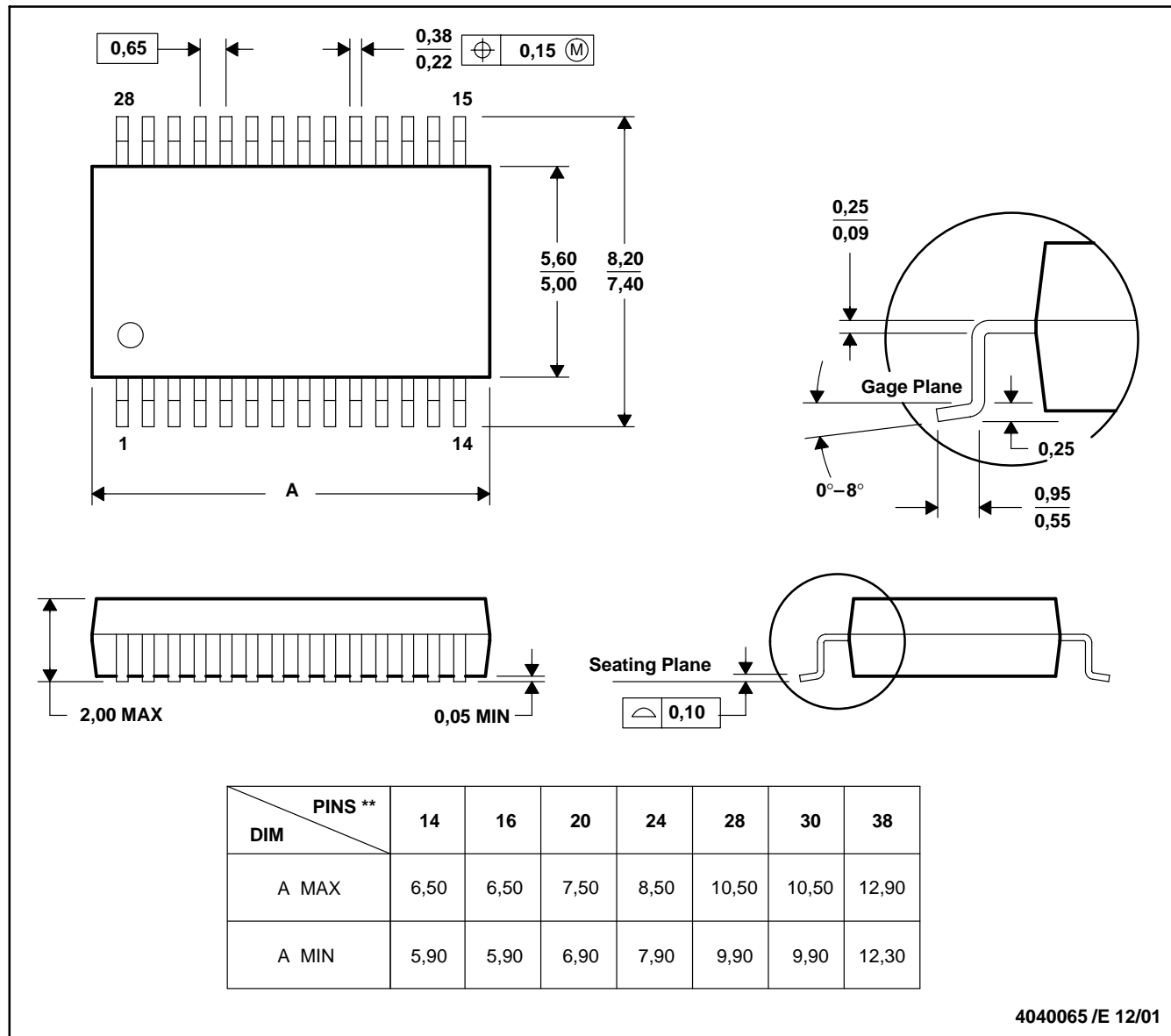
# MECHANICAL DATA

MSS0002E – JANUARY 1995 – REVISED DECEMBER 2001

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

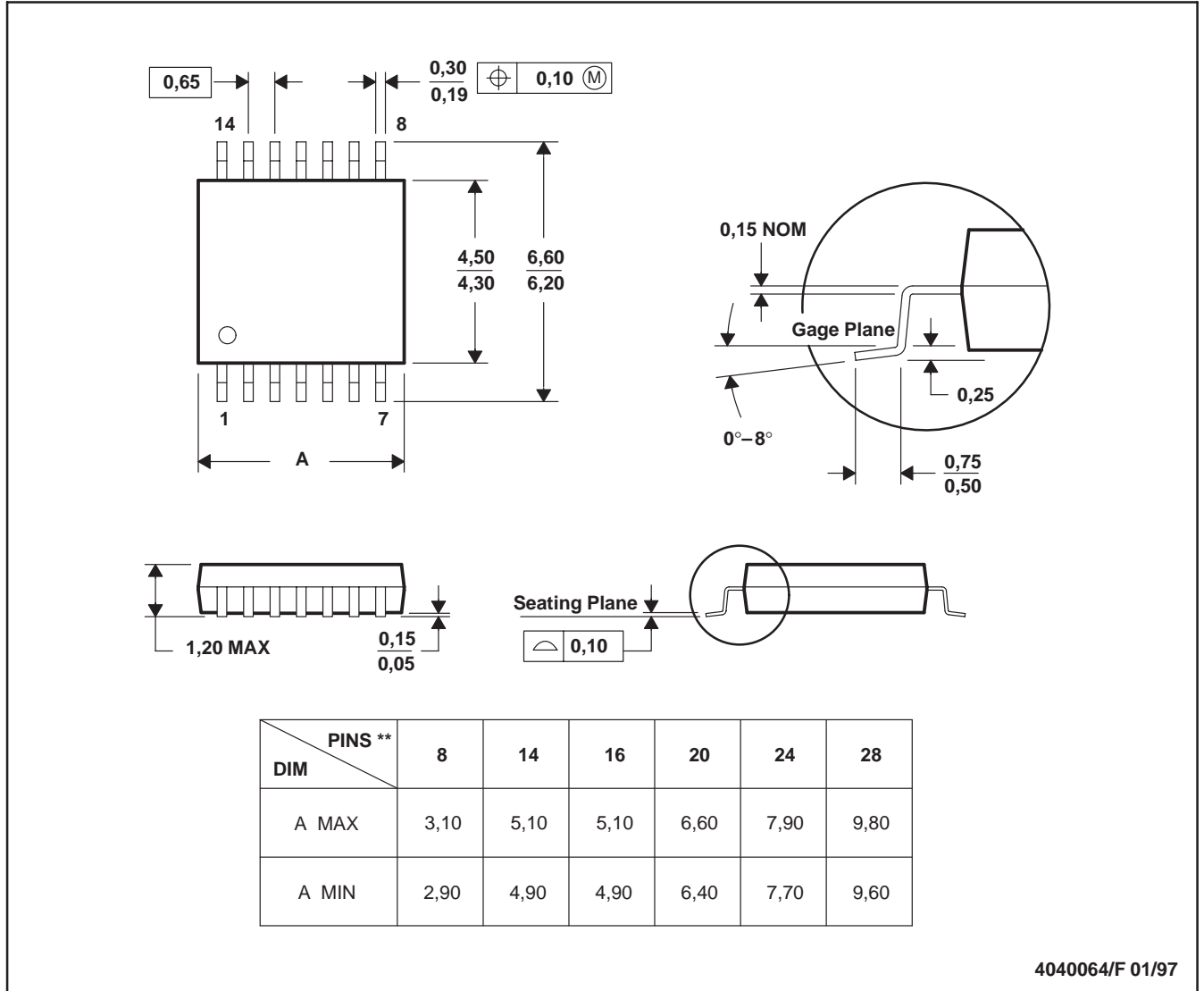
# MECHANICAL DATA

MTSS001C – JANUARY 1995 – REVISED FEBRUARY 1999

**PW (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153



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Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>	Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>	Telephony	<a href="http://www.ti.com/telephony">www.ti.com/telephony</a>
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